

GSM7002KAF

60V N-Channel Enhancement Mode MOSFET

Product Description

GSM7002K, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

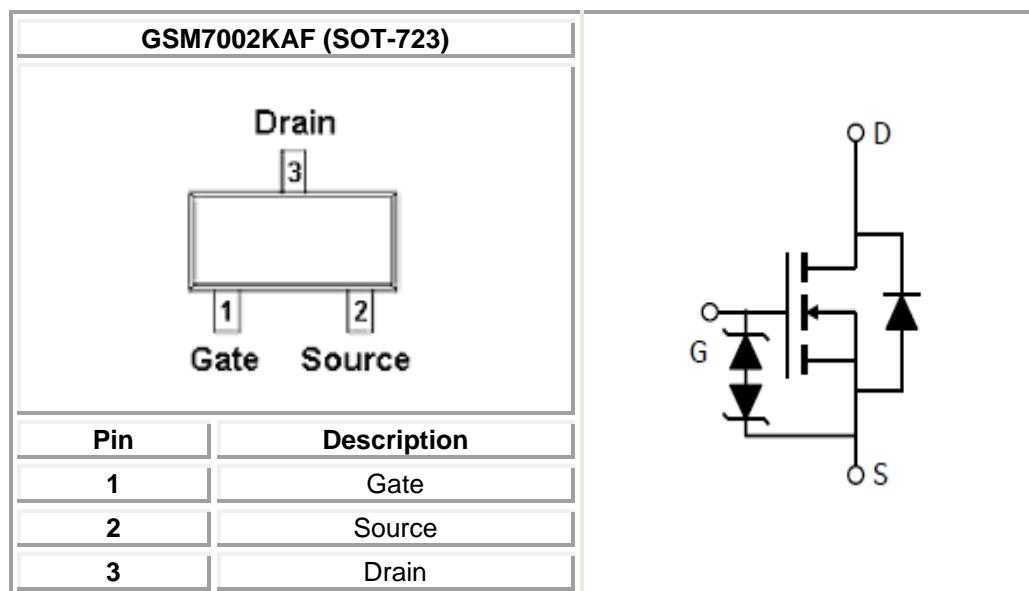
Features

- 60V/0.5A , $R_{DS(ON)}=3.0\Omega @ V_{GS}=10V$
- 60V/0.2A , $R_{DS(ON)}=4.0\Omega @ V_{GS}=4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-723 package design

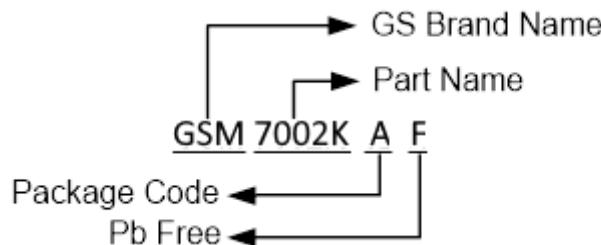
Applications

- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- High saturation current capability.
- Direct Logic-Level Interface: TTL/CMOS
- Battery Operated Systems
- Solid-State Relays

Packages & Pin Assignments



Ordering and Marking Information



Part Number	Package	Part Marking	Quantity
GSM7002KAF	SOT-723	RK	8000 PCS

Absolute Maximum Ratings

T_A=25°C Unless otherwise noted

Symbol	Parameter	Typical	Unit
V _{DSS}	Drain-Source Voltage	60	V
V _{GSS}	Gate-Source Voltage - Continuous	±20	V
I _D	Continuous Drain Current	T _A =25°C	0.15
		T _A =70°C	0.13
P _D	Power Dissipation	T _A =25°C	0.16
		T _A =70°C	0.1
T _J	Operating Junction Temperature	-55/150	°C
T _{STG}	Storage Temperature Range	-55/150	°C
R _{θJA}	Thermal Resistance-Junction to Ambient	833	°C/W

Electrical Characteristics

$T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Static							
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	60			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0		2.0		
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			10	uA	
		$V_{DS}=0\text{V}, V_{GS}=\pm 10\text{V}$			200	nA	
		$V_{DS}=0\text{V}, V_{GS}=\pm 5\text{V}$			100	nA	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=48\text{V}, V_{GS}=0\text{V}$			1	uA	
$R_{DS(\text{on})}$	Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=0.5\text{A}$		1.3	3	Ω	
		$V_{GS}=4.5\text{V}, I_D=0.2\text{A}$		1.4	4		
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}, I_S=0.2\text{A}$		0.97	1.5	V	
Q_{rr}	Recovered Charge	$V_{GS}=0\text{V}, I_S=300\text{mA}, V_R=25\text{V}$, $dI/dt=-100\text{A}/\mu\text{s}$		30		nC	
t_{rr}	Reverse Recovery Time	$V_{GS}=0\text{V}, I_S=300\text{mA}, V_R=25\text{V}$, $dI/dt=-100\text{A}/\mu\text{s}$		30		ns	
Dynamic							
Q_g	Total Gate Charge	$V_{DD}=10\text{V}, I_D=0.25\text{A}, V_{GS}=4.5\text{V}$		500			
Q_{gs}	Gate-Source Charge			100		pC	
Q_{gd}	Gate-Drain Charge			150			
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}, f=1\text{MHz}, V_{GS}=0\text{V}$		30			
C_{oss}	Output Capacitance			8		pF	
C_{rss}	Reverse Transfer Capacitance			5			
$t_{d(\text{on})}$	Turn-On Time	$V_{DD}=30\text{V}, I_D=0.2\text{A}, R_G=10\Omega, V_{GEN}=4.5\text{V}, R_L=150\Omega$		10	20		
t_r				35	50		
$t_{d(\text{off})}$	Turn-Off Time			20	30	ns	
t_f				40	60		

Typical Performance Characteristics

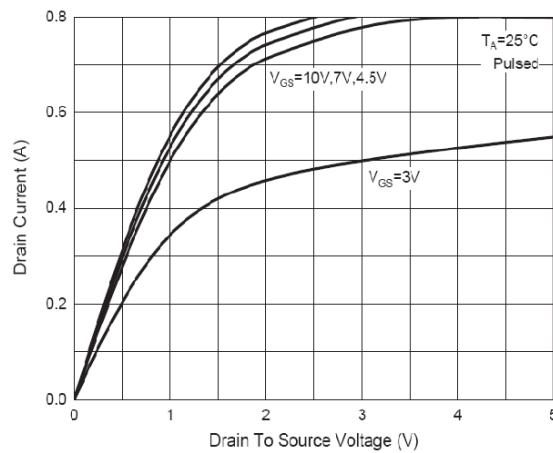


Fig. 1 Typical Output Characteristics

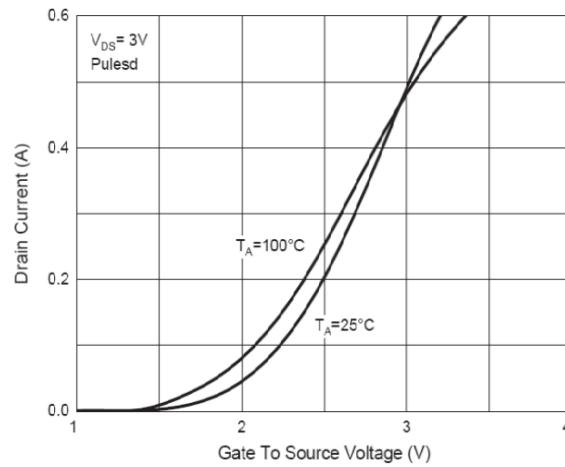


Fig. 2 Typical Transfer Characteristics

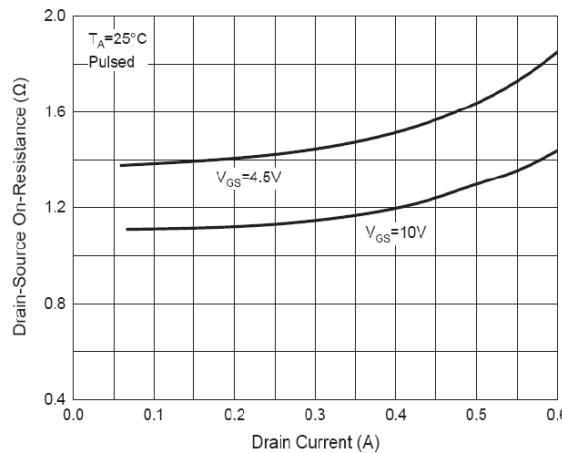


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

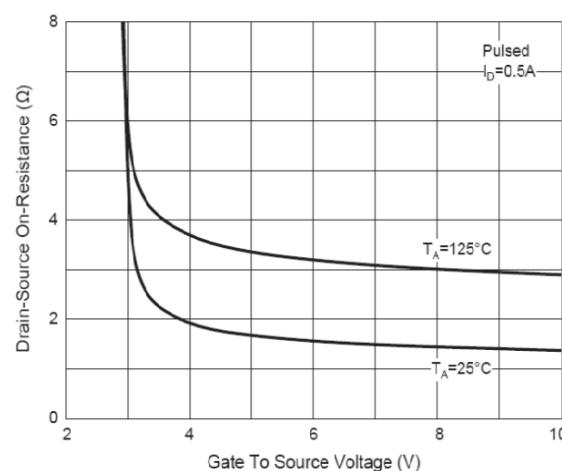


Fig. 4 Typical Transfer Characteristic

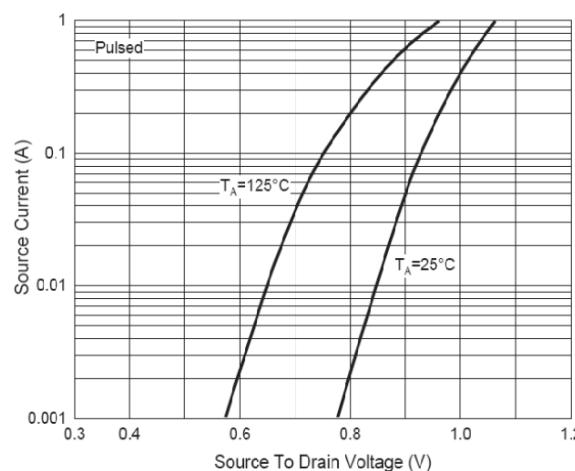


Fig. 5 Diode Forward Voltage vs. Current

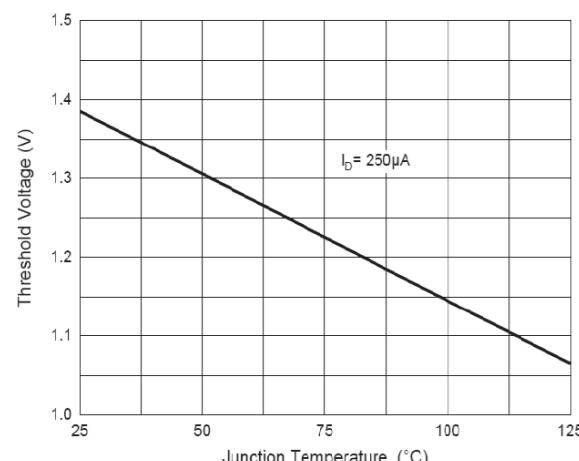
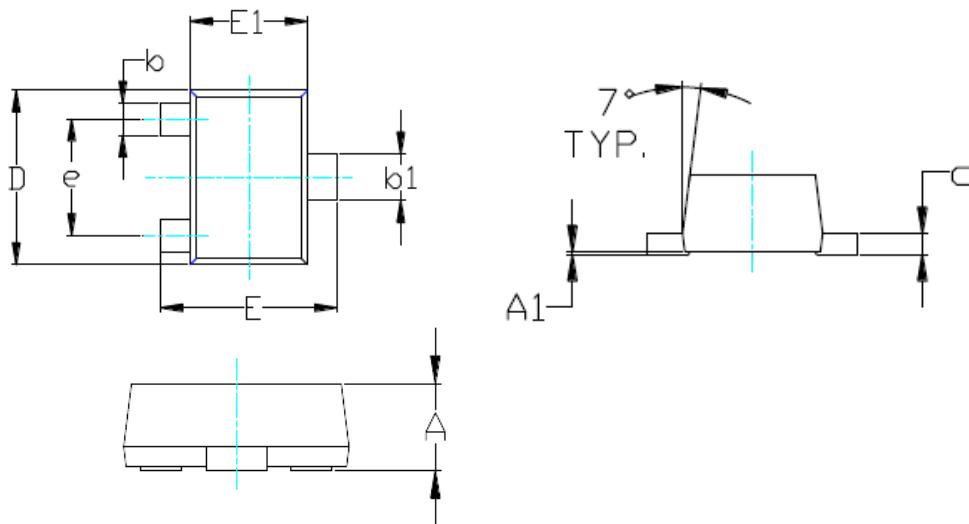


Fig. 6 Gate Threshold Variation vs. T_J

Package Dimension

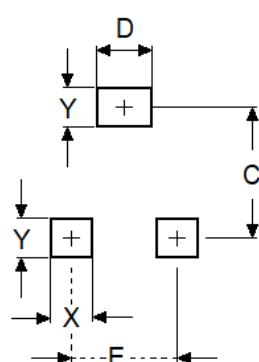
SOT-723



Dimensions

Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.430	0.500	-	0.020
A1	0.000	0.050	0.000	0.002
b	0.170	0.270	0.007	0.011
b1	0.270	0.370	0.011	0.015
c	0.080	0.150	-	0.006
D	1.150	1.250	0.045	0.049
E	1.150	1.250	0.045	0.049
E1	0.750	0.850	0.030	0.033
e	0.800 TYP		0.031 TYP	
θ	7° REF		7° REF	

Suggested Pad Layout



DIMENSIONS	VALUE (IN MM)
C	1.00
D	0.42
E	0.80
X	0.32
Y	0.30

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